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**Question Paper Code:U2912**

Ph.D. COURSE WORK EXAMINATION, MAY 2024

Electives

Communication Systems

21PCM512- MICROELECTRONICS AND VLSI TECHNOLOGY

(Regulations 2021)

Duration: Three hours

Maximum: 100 Marks

Answer ALL Questions

PART - A (5 x 20 = 100 Marks)

1. (a) For a free electron with a velocity of  $10^7$  cm/s, what is its de Broglie wavelength? (b) In GaAs, the effective mass of electrons in the conduction band is  $0.063 m_0$ . If they have the same velocity, find the corresponding de Broglie wavelength. CO3- App (20)

Or

- (b) A metal, with a work function  $\phi_m = 4.2$  V, is deposited on an n-type silicon semiconductor with affinity  $\chi = 4.0$  V and  $E_g = 1.12$  eV. What is the potential barrier height seen by electrons in the metal moving into the semiconductor? CO3- App (20)

2. (a) A particular silicon device needs to have an implant of boron with a peak at a depth of  $0.3\mu\text{m}$  and a peak concentration of  $10^{17}$   $\text{cm}^{-3}$ . Determine the implant energy and dose that should be used for this process. Find the as – implanted junction depth if the substrate is n-type with a concentration of  $10^{15}$   $\text{cm}^{-3}$ . CO3- App (20)

Or

- (b) A typical high current implanter operates with an ion beam of 2mA. How long would it take to implant a 150 mm- diameter wafer with  $\text{O}^+$  to a dose of  $1 * 10^{18}$   $\text{cm}^{-2}$ ? CO3- App (20)

3. (a) Certain resists have contrast as large as 7. If a positive tone resist has  $D_0 = 10\text{mJ}/\text{cm}^2$  and has  $\gamma = 7$ . Find  $D_{100}$ . For some applications to make a tapered resist profile, that is, a resist edge that is not vertical, but rather rises more slowly from the exposed region. To do this would you a high dose illumination or a low dose illumination? Justify your answer. What limits the exposure? CO5- Ana (20)

Or

- (b) A  $\langle 100 \rangle$ -oriented silicon wafer 150 mm in diameter is 625  $\mu\text{m}$  thick. CO5- Ana (20)  
The wafer has  $1000 \mu\text{m} \times 1000 \mu\text{m}$  ICs on it. The IC chips are to be separated by orientation-dependent etching. Describe two methods for doing this and calculate the fraction of the surface area that is lost in these processes.
4. (a) Given a switch box, develop an efficient algorithm to find the minimum diameter of rectilinear Steiner trees. The diameter of a tree is the maximum distance between any two of its vertices CO5- Ana (20)  
Or  
(b) Prove that for  $n = 3$ , single trunk Steiner tree is indeed an optimal rectilinear Steiner tree. CO5- Ana (20)
5. (a) Describe Landauer- Büttiker Formalism for Conduction in Confined Structures CO2- U (20)  
Or  
(b) Explain Ballistic Quantum Transport in Semiconductor Nanostructures CO2- U (20)